Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .004” min.**

**Backside Potential: Collector**

**Mask Ref: 004842**

**APPROVED BY: DK DIE SIZE .015” X .018” DATE: 11/16/21**

**MFG: FAIRCHILD THICKNESS .008” P/N: MMBT3904**

**DG 10.1.2**

#### Rev B, 7/19/02